

ASSIGNMENT

WHEREAS, I, as a below named inventor, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan and Sony Electronics Inc. a Delaware corporation with offices at 1 Sony Drive, Park Ridge, New Jersey 07656 (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignees of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEES thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

And I hereby authorize and request my attorney(s) of record in this application to insert the execution date, serial number and filing date of this application in the spaces that follow: Serial Number: 101052, 199, Filing Date: 12-5-01.

This assignment is being executed on the date indicated below.

Shin Fujimori

Dated: 2-18-02

This assignment is being executed on the date indicated below

Hiyouki Nakazono

Dated: _____

This assignment is being executed on the date indicated below

Toshinori Hamada

Dated: 2-18-02

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Hiyouki Nakazono

Dated: 2/12/02

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Toshinori Hamada

Dated: _____

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the U. S. Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

S. Fujimori
Inventor's signature

2-18-02
Date

Shin Fujimori
Name of sole or first inventor

San Diego, CA 92129
Residence (City, State)

13485 Thunderhead Street, San Diego, CA 92129
Post Office Address

Japan
Citizenship

Inventor's signature

Date

Hiyouki Nakazono
Name of sole or first inventor

2-28-1 Edanishi, Aoba-ku, Yokohama, Kanagawa, Japan 225-0014
Post Office Address

Japan
Citizenship

T. Hamada
Inventor's signature

2-18-02
Date

Toshinori Hamada
Name of sole or first inventor

San Diego, CA 92127
Residence (City, State)

18195 Moon Song Court, San Diego, CA 92127
Post Office Address

Japan
Citizenship

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under §1001 of Title 18 of the U. S. Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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San Diego, CA 92129

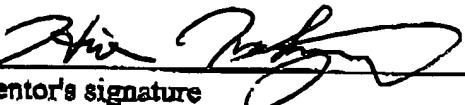
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13485 Thunderhead Street, San Diego, CA 92129

Post Office Address

Japan

Citizenship



Inventor's signature

Hivouki Nakazono

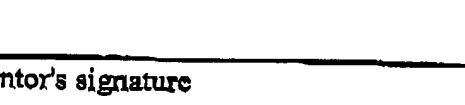
Name of sole or first inventor

2-28-1 Edanishi, Aoba-ku, Yokohama, Kanagawa, Japan 225-0014

Post Office Address

Japan

Citizenship



Inventor's signature

2/12/02

Date

Toshinori Hamada

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San Diego, CA 92127

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